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Serial Number: 10/822064

- 1.) See attached printout of inventors listed in PALM**

- 2.) See attached EAST Inventor Search**
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Day : Friday
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PALM INTRANET

Inventor Information for 10/822064

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|-------------------------|----------|---|----------|--|-----------------------|
| US 20050283745 A1 | 20051222 | Design checks for signal lines | 716/4 | | Meyer, Neal et al. |
| US 20050223552 A1 | 20051013 | Bonding an interconnect to a circuit device and related devices | 29/832 | 257/E23.004; 257/E23.078; 29/833; 29/834 | Meyer, Neal et al. |
| US 7100135 B2 | 20060829 | Method and system to evaluate signal line spacing | 716/5 | | Meyer; Neal et al. |
| US 6605821 B1 | 20030812 | Phase change material electronic memory structure and method for forming | 257/2 | 257/1; 257/3; 257/4; 257/E27.004; 438/900 | Lee; Heon et al. |
| US 5937494 A | 19990817 | Method for assembling an ink-jet pen having a double-sided electrical interconnect flexible circuit | 29/25.35 | 257/E23.177; 29/611; 29/890.1 | Meyer; Neal et al. |
| US 5612511 A | 19970318 | Double- sided electrical interconnect flexible circuit for ink-jet hard copy systems | 174/254 | 174/262; 257/E23.177; 347/50; 361/749; 361/767 | Meyer; Neal et al. |